L Number	Hits	Search Text	DB	Time stamp	
1	11	(("5242855") or ("3918148") or ("6175084")	USPAT;	2004/10/08	11:34
		or ("5134539") or ("6297553") or	US-PGPUB		
		("5143865") or ("6389689") or ("6479887")			
	ĺ	or ("6252298") or ("6268236") or			
	1.0	("20010052642")).PN.		0004/10/00	
2	18			2004/10/08	09:53
	1	and test\$6 and (dic\$4) and magnetic\$6 and @ad<20000616	US-PGPUB; EPO; JPO;		
		@dd\20000010	DERWENT;		
	İ		IBM TDB		
4	88	438/\$.ccls. and align\$6 and test\$6 and	USPĀT;	2004/10/08	09:54
		(dic\$4) and magnetic\$6 and @ad<20000616	US-PGPUB;		
		·	EPO; JPO;		
			DERWENT;		
5		420/6 cala and /alima66 came teatife came	IBM_TDB	2004/10/00	00-54
5	١	438/\$.ccls. and (align\$6 same test\$6 same (dic\$4) same magnetic\$6) and @ad<20000616	USPAT; US-PGPUB;	2004/10/08	09:54
		(dicy4) same magneticy0) and Gad\20000010	EPO; JPO;		
			DERWENT;		
			IBM TDB		
6	0	438/\$.ccls. and (align\$6 with test\$6 with	USPĀT;	2004/10/08	09:55
,		(dic\$4) with magnetic\$6) and @ad<20000616	US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
l. 7	0	438/\$.ccls. and (align\$6 near test\$6 near	IBM_TDB	2004/10/00	00.55
'	١	(dic\$4) near magnetic\$6) and @ad<20000616	USPAT; US-PGPUB;	2004/10/08	09:55
		(dicy4) Hear magneticy0) and gad<20000010	EPO; JPO;		
			DERWENT;		
			IBM TDB		
8	0	257/\$.ccls. and (align\$6 near test\$6 near	USPĀT;	2004/10/08	09:55
		(dic\$4) near magnetic\$6) and @ad<20000616	US-PGPUB;		
			EPO; JPO;		
			DERWENT;		
9	0	semiconductor and (align\$6 near test\$6	IBM_TDB USPAT;	2004/10/08	09.56
		near (dic\$4) near magnetic\$6) and	US-PGPUB;	2004/10/00	09.30
		@ad<20000616	EPO; JPO;		
			DERWENT;		
_			IBM_TDB		
3	13	438/455, 456, 457, 458, 459, 460, 461, 462, 464.ccl		2004/10/08	10:00
		and align\$6 and test\$6 and (dic\$4) and	US-PGPUB;		
		magnetic\$6 and @ad<20000616	EPO; JPO; DERWENT;		
			IBM TDB		
10	28	438/15,113,110,107,108,114,123,455,456,457,	155PAT9,460,	48004620468.	. £6161
		and align\$6 and test\$6 and (dic\$4) and	US-PGPUB;		
		magnetic\$6 and @ad<20000616	EPO; JPO;		
			DERWENT;		
11	1	("6165885").PN.	<pre>IBM_TDB USPAT;</pre>	2004/10/08	11.24
**		(010000).IN.	US-PGPUB	2004/10/08	11:34
_	348	(438/15).CCLS.	USPAT	2004/04/08	08:51
	258	(438/113).CCLS.	USPAT	2002/07/03	
-	94	(438/110).CCLS.	USPAT	2002/07/03	
-	59	(438/114).CCLS.	USPAT	2002/07/03	
_	681	438/15,110,113,114.ccls.	USPAT	2002/12/19	
_	401 272	438/15,110,113,114.ccls. and test\$3 (438/15,110,113,114.ccls. and test\$3) and	USPAT USPAT	2001/08/07 2001/08/07	
	212	(dice\$4 or cut\$5)	ODEMI	2001/00/07	10.10
_	901	438/15,110,113,114.ccls.	USPAT;	2002/02/04	09:53
			EPO; JPO;	,	
			DERWENT		İ
-	460	438/15,110,113,114.ccls. and test\$3	USPAT;	2002/02/04	09:54
l			EPO; JPO;		
_	325	(439/15 110 113 114 colo and tootes) and	DERWENT	2004/10/06	00.25
-	323	(438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5)	USPAT; EPO; JPO;	2004/10/06	09:25
		(41010 01 04640)	DERWENT		
-	5	(("6077757") or ("6335224") or ("6309943")	USPAT	2004/04/08	10:12
		or ("6309909") or ("6326697")).PN.			

_	7	(("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or	USPAT	2002/02/05 09:49
-	326	("5858815") or ("5137836")).PN (438/15,110,113,114.ccls. and test\$3) and (dic\$5 or cut\$5)	USPAT; EPO; JPO;	2004/10/07 12:10
-	0		DERWENT USPAT; EPO; JPO;	2002/02/05 08:33
_	170	align\$5) ((438/15,110,113,114.ccls. and test\$3) and	DERWENT USPAT;	2002/02/05 08:32
_	2705	(dic\$5 or cut\$5)) and (align\$5) magnet\$7 adj align\$5	EPO; JPO; DERWENT USPAT;	2002/02/05 08:56
_	0	(magnet\$7 adj align\$5) and (wafer adj20	EPO; JPO; DERWENT USPAT;	2002/02/05 08:37
_	0	dielectric adj tape)	EPO; JPO; DERWENT USPAT;	2002/02/05 08:37
			EPO; JPO; DERWENT	
-	0	wafer adj dielectric adj tape	USPAT; EPO; JPO; DERWENT	2002/02/05 08:38
	_ 248	(magnet\$7 adj align\$5) and semiconductor	USPAT; EPO; JPO; DERWENT	2002/02/05 08:57
_	0	((magnet\$7 adj align\$5) and ring) and (charged adj slot)	USPAT; EPO; JPO; DERWENT	2002/02/05 08:49
_	0	(magnet\$7 adj align\$5) and (charged adj slot)	USPAT; EPO; JPO;	2002/02/05 08:49
_	613	(magnet\$7 adj align\$5) and ring	DERWENT USPAT; EPO; JPO;	2002/02/05 08:50
_	47	((magnet\$7 adj align\$5) and ring) and semiconductor	DERWENT USPAT; EPO; JPO;	2002/02/05 08:51
_	3066	optically adj align\$5	DERWENT USPAT; EPO; JPO;	2002/02/05 08:56
_	612	(optically adj align\$5) and semiconductor	DERWENT USPAT; EPO; JPO;	2002/02/05 08:57
-	8	(("6077757") or ("6335224") or ("6309943") or ("6309909") or ("6326697") or ("5858815") or ("5137836") or	DERWENT USPAT	2003/06/02 08:10
_	10260	("4781969")).PN. wood.inv.	USPAT; US-PGPUB;	2002/07/03 08:13
			EPO; JPO; DERWENT;	
_	539	wood.inv. and alan	IBM_TDB USPAT; US-PGPUB;	2002/07/03 08:13
			EPO; JPO; DERWENT; IBM_TDB	0000405405
_	232	(wood.inv. and alan) and (micron adj technology)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/07/03 08:14
-	1 425	("6268650").PN. (438/15).CCLS.	IBM_TDB USPAT USPAT	2004/04/06 13:58 2002/07/08 08:43
-	331	(438/13).CCLS.	USPAT	2002/07/08 08:57
_	140	(438/113).CCLS.	USPAT	2002/07/08 08:57
_	90	(438/114).CCLS.	USPAT	2002/07/08 08:57
-	425	(438/15).CCLS.	USPAT	2002/07/08 08:43
-	331	(438/113).CCLS.	USPAT	2002/07/08 08:57
L	140	(438/110).CCLS.	USPAT	2002/07/08 08:57

	1	T	0000100100
- 90 - 13	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	USPAT USPAT	2002/07/08 14:32 2002/07/08 10:35
	("5858815") or ("5817535") or ("5770032") or ("4781969") or ("5073840") or		
	("5696033") or ("5834839") or ("6160714")).PN.		
8	or ("6077757") or ("6326697") or ("6165885") or ("5834320") or	USPAT	2002/07/09 09:56
o	("4781969")).PN. (wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3 same (cut\$4 or dic\$3 or separat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/12/19 15:00
0	<pre>(wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3 same (cut\$4 or dic\$3 or separat\$3)</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/19 14:07
- 19	<pre>wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/12/19 14:07
- 0	(wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/12/19 14:38
- 963 - 1212	438/15,110,113,114.ccls. 438/15,110,113,114.ccls.	IBM_TDB USPAT; USPAT; US-PGPUB; EPO; JPO;	2002/12/19 14:38 2002/12/19 14:38
- 0	438/15,110,113,114.ccls. and ((wafer adj (bond\$3 or attach\$3) near4 (dielectric adj (layer or film))) same test\$3)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/12/19 14:40
9	(wafer adj (dielectric adj (layer or film))) same test\$3	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/12/20 08:18
- 13	or ("5977629") or ("6326700") or ("6268650") or ("5858815") or ("5817535") or ("5770032") or ("5796170") or ("4781969") or ("5073840") or	IBM_TDB USPAT	2002/12/19 15:19
- 85	("5696033")).PN. wafer same dielectric same test\$3 same (cut\$3 or dic\$3 or slic\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/12/20 08:42
78	(wafer same dielectric same test\$3 same (cut\$3 or dic\$3 or slic\$3)) and semiconductor	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2002/12/20 09:38
- 348	<pre>(wafer same (dielectric adj (layer or film))) same test\$3</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/12/20 09:35

_	322	((wafer same (dielectric adj (layer or film))) same test\$3) and semiconductor	USPAT; US-PGPUB;	2002/12/20 09:38
		TITM())) Same testss) and semiconductor	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000 (40 (00 00 00
_	98	<pre>(((wafer same (dielectric adj (layer or film))) same test\$3) and semiconductor)</pre>	USPAT; US-PGPUB;	2002/12/20 09:39
		and (cut\$3 or dic\$3)	EPO; JPO;	
			DERWENT;	
	_	, m c 4 0 4 0 0 0 m	IBM_TDB	0000 (10 (00 10 0)
-	1 3		USPAT USPAT	2002/12/20 10:24 2002/12/23 11:53
_		("6389689")).PN.	USERI	2002/12/23 11.33
-	2	(("5897337") or ("6389689")).PN.	USPAT	2002/12/23 11:53
-	9187	((balls adj grid adj arrays) or (BGA)) and	USPAT;	2003/05/20 07:59
		semiconductor	US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	4418	(((balls adj grid adj arrays) or (BGA))	USPAT;	2003/05/20 08:02
		and semiconductor) and (dic\$4 or cut\$4 or separat\$5)	US-PGPUB; EPO; JPO;	
		Separacyo	DERWENT;	
			IBM_TDB	
-	4476		USPAT;	2003/05/20 08:04
		and semiconductor) and (dic\$4 or cut\$4 or separat\$5 or saw\$4)	US-PGPUB; EPO; JPO;	
		Separate of Same 17	DERWENT;	
			IBM_TDB	
-	955	((((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or	USPAT; US-PGPUB;	2003/05/20 08:04
		separat\$5)) and (metal adj (film or	EPO; JPO;	· ·
		layer))	DERWENT;	
			IBM_TDB	
_	970	((((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or	USPAT; US-PGPUB;	2003/05/20 08:04
	į	separat\$5 or saw\$4)) and (metal adj (film	EPO; JPO;	
		or layer))	DERWENT;	
	,	/#20010052642#\ PM	IBM_TDB US-PGPUB	2003/05/20 08:12
	1 472	• •	USPAT;	2003/05/20 08:12
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	2000,00,20 00,02
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)	DERWENT; IBM TDB	
_	233	(wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12 08:09
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616	DERWENT; IBM TDB	
-	212	((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 08:23
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or	EPO; JPO; DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	·
		or cut\$6 or saw\$5)		
-	206		USPAT;	2003/05/20 09:06
		and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or (BGA)) and	US-PGPUB; EPO; JPO;	
	·	semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
_	1	or cut\$6) (((wafer adj semiconductor) same (metal	IICDAT.	2003/05/20 10:06
-		adj (film or layer)) same (attach\$5 or	USPAT; US-PGPUB;	2003/03/20 10:00
		bond\$4) same ((balls adj grid adj arrays)	EPO; JPO;	
	İ	or (BGA)) same (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) same (dic\$5 or cut\$6 or saw\$5)) and @ad<=20000616	IBM_TDB	
L		- Dany 5// and Gad - 20000010		

	•			
-	212	((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:00
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)		
-	172	(((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:24
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5 or cut\$6 or saw\$5)) and dic\$5	IBM_TDB	
 _	92	(((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:35
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	2003703721 03:33
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5)) and (dicing or diced)	_	
-	70	((((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:36
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)) and (dicing or		
	70	diced)) and (individual\$3 or each)	IICDAM.	2002/05/21 00-26
	'	((((wafer and (metal adj (film or layer)) and (attach\$5 or bond\$4) and ((balls adj	USPAT; US-PGPUB;	2003/05/21 09:36
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5)) and (dicing or	_	
		diced)) and (individual\$3)		
-	6	((((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:37
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)) and (dicing or diced)) and (individual\$3 adj device)		
_	2	(("6344401") or ("6566745")).PN.	USPAT	2004/01/12 07:56
_	241	(wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12 08:10
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or ("BGA")) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616	IBM_TDB	
_	1	((wafer same (metal adj (film or layer))	USPĀT;	2003/10/23 10:36
		same (attach\$5 or bond\$4) same ((balls adj	US-PGPUB;	
		grid adj arrays) or ("BGA")). same	EPO; JPO;	
		semiconductor same (dic\$4 or cut\$4 or separat\$5))) and @ad<=20000616	DERWENT;	
_	2	(("6153448") or ("20020011859")).PN.	USPAT;	2003/10/24 12:35
			US-PGPUB	2000,10,24 12.00
-	4	(("6153448") or ("20020011859") or	USPAT;	2003/10/24 14:07
		("6064217") or ("5475317")).PN.	US-PGPUB	
-	3	(("6344401") or ("6165885") or	USPAT	2004/01/12 09:14
		("5834320")).PN.		
-	244	(wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12 08:03
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
1		and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616	DERWENT;	
_	244	<pre>(wad<=20000616 (wafer and (metal adj (film or layer)) and</pre>	IBM_TDB USPAT;	2004/04/06 08:33
-	244	(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	2004/04/00 08:33
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616	IBM TDB	
-	166	((wafer and (metal adj (film or layer))	USPĀT;	2004/01/12 08:05
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
]		separat\$5)) and @ad<=20000616) and	IBM_TDB	
L	L	align\$6	L	

·					
_	688	(438/455).CCLS.	USPAT; US-PGPUB;	2004/01/12	08:08
			EPO; JPO;		
			DERWENT;		
			IBM TDB		
_	12	438/455,456,457,458,459,460,461,462,464.ccl		2004/10/06	09:26
		and (wafer and (metal adj (film or layer))	US-PGPUB;		
		and (attach\$5 or bond\$4) and ((balls adj	EPO; JPO;		
		grid adj arrays) or ("BGA")) and (dic\$4 or	DERWENT;		
		cut\$4 or separat\$5)) and @ad<=20000616	IBM_TDB	0004/10/06	00 00
_	97	438/\$.ccls. and (wafer and (metal adj	USPAT;	2004/10/06	09:23
		(film or layer)) and (attach\$5 or bond\$4) and ((balls adj grid adj arrays) or	US-PGPUB; EPO; JPO;		
		("BGA")) and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616	IBM TDB		
_	348	(wafer and ((metal or conductive) adj	USPAT;	2004/04/06	08:36
		(film or layer)) and (attach\$5 or bond\$4)	US-PGPUB;		
		and ((balls adj grid adj arrays) or (BGA))	EPO; JPO;		
		and semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616	IBM_TDB		
-	229	((wafer and ((metal or conductive) adj	USPĀT;	2004/04/06	08:36
1		(film or layer)) and (attach\$5 or bond\$4)	US-PGPUB;		
		<pre>and ((balls adj grid adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or</pre>	EPO; JPO; DERWENT;		
		separat\$5)) and @ad<=20000616) and	IBM TDB		
		test\$4			
_	85	(((wafer and ((metal or conductive) adj	USPAT;	2004/04/06	08:37
		(film or layer)) and (attach\$5 or bond\$4)	US-PGPUB;		
		and ((balls adj grid adj arrays) or (BGA))	EPO; JPO;		
		and semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
	1	separat\$5)) and @ad<=20000616) and	IBM_TDB		
	86	test\$4) and (input same output)	IICDAT.	2004/04/06	Ω.44
-	80	(((wafer and ((metal or conductive) adj (film or layer)) and (attach\$5 or bond\$4)	USPAT; US-PGPUB;	2004/04/06	00:44
	İ	and ((balls adj grid adj arrays) or (BGA))	EPO; JPO;		
		and semiconductor and (dic\$4 or cut\$4 or	DERWENT;		
		separat\$5)) and @ad<=20000616) and	IBM TDB		•
		test\$4) and (input and output)	_		
-	78	((((wafer and ((metal or conductive) adj	USPAT;	2004/04/06	11:21
		(film or layer)) and (attach\$5 or bond\$4)	US-PGPUB;		
	·	and ((balls adj grid adj arrays) or (BGA))	EPO; JPO;		
		and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and @ad<=20000616) and	DERWENT; IBM TDB		
		test\$4) and (input and output)) and (cut\$5	TDI-1_10D		
		or dic\$6)			
-	24	(((((wafer and ((metal or conductive) adj	USPAT;	2004/04/06	11:21
		(film or layer)) and (attach\$5 or bond\$4)	US-PGPUB;		
		and ((balls adj grid adj arrays) or (BGA))	EPO; JPO;		
		and semiconductor and (dic\$4 or cut\$4 or	DERWENT;	·	•
	1	separat\$5)) and @ad<=20000616) and	IBM_TDB		
	<u> </u>	test\$4) and (input and output)) and (cut\$5	!		
_	5	or dic\$6)) and (conductive adj trace) (("5858815") or ("4781969") or ("5073840")	USPAT	2004/04/08	13.56
		or ("5770032") or ("5817535")).PN.	JULAI	2003/03/00	13.30
_	10	(("5073840") or ("5817535") or ("5858815")	USPAT	2004/04/08	13:29
		or ("6426642") or ("6214716") or			– -
1	,	("6188232") or ("6163956") or ("6150193")			
		or ("6060891") or ("6004867")).PN.			
-	10	(("5073840" "5817535" "5858815" "6426642"	USPAT;	2004/04/08	09:30
		"6214716" "6188232" "6163956" "6150193"	US-PGPUB;		
		"6060891" "6004867").pn.) and test\$5 and	EPO; JPO;		
1		(cut\$5 or dic\$6 or seperat\$5 or saw\$4)	DERWENT; IBM TDB		
 _	6	((("5073840" "5817535" "5858815" "6426642"	USPAT;	2004/04/08	09:30
		"6214716" "6188232" "6163956" "6150193"	US-PGPUB;		,
		"6060891" "6004867").pn.) and test\$5 and	EPO; JPO;		
		(cut\$5 or dic\$6 or seperat\$5 or saw\$4))	DERWENT;		
		and cut\$6	IBM_TDB		

<u> </u>	1134	,	USPAT;	2004/10/06 09:25
		@ad<20000616	US-PGPUB;	
			EPO; JPO;	
į			DERWENT;	
1			IBM TDB	
_	2169	257/\$.ccls. and test\$6 and (dic\$4) and	USPAT;	2004/10/06 09:25
		@ad<20000616	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	203	438/15,110,113,114.ccls. and test\$6 and	USPAT;	2004/10/06 09:25
		(dic\$4) and @ad<20000616	EPO; JPO;	
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-	199	438/455,456,457,458,459,460,461,462,464.ccl	SUSPAT;	2004/10/08 09:53
		and test\$6 and (dic\$4) and @ad<20000616	US-PGPUB;	
			EPO; JPO;	
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-	2	("6261919").PN.	USPAT;	2004/10/06 13:56
	· ·		US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
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-	2	("6429530").PN.	USPAT;	2004/10/07 08:13
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			EPO; JPO;	
ľ			DERWENT;	
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-	7	(("6163956") or ("6153448") or ("6064217")	USPAT;	2004/10/07 10:04
1		or ("6344401") or ("4781969") or	US-PGPUB	
		("5137836") or ("20010052642")).PN.		
_	1	("5989982").PN.	USPAT;	2004/10/07 13:52
			US-PGPUB	
	1	("5897334").PN.	USPAT;	2004/10/07 13:52
			US-PGPUB	